Title (en)
METHOD FOR BONDING AND RELEASING SUBSTRATES

Title (de)
VERFAHREN ZUM BONDEN UND LÖSEN VON SUBSTRATEN

Title (fr)
PROCÉDÉ DE LIAISON ET DE DÉTACHEMENT DE SUBSTRATS

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Abstract (en)
[origin: WO2017076682A1] The invention relates to a method for bonding a product substrate (2) with a connection layer (4) to a support substrate (5) and to a method for releasing the product substrate from the support substrate. A release layer (3) is applied between the connection layer (4) and the product substrate (2), wherein • a) the release layer (3) can be released by interacting with an electromagnetic radiation of a radiation source, and • b) the connection layer (4) and the support substrate (5) is each at least largely transparent to the electromagnetic radiation. The invention further relates to a corresponding product substrate/support substrate composite.

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